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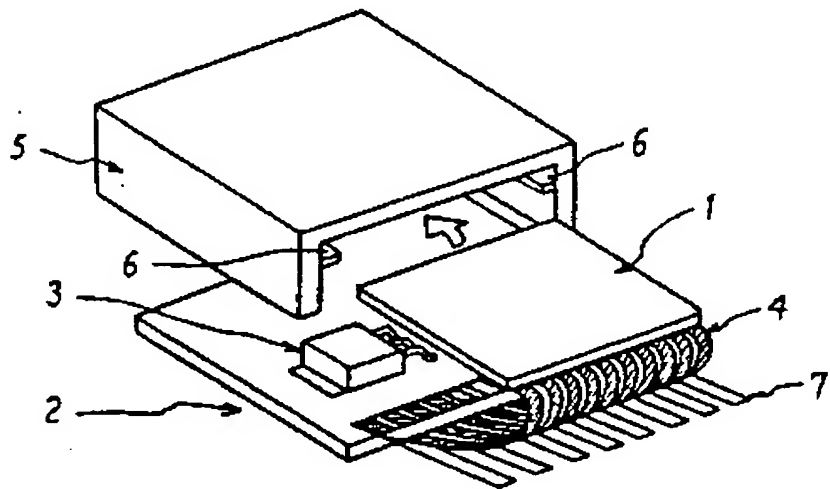
(54) POWER HYBRID INTEGRATED CIRCUIT

(57) Abstract:

PURPOSE: To enhance reliability of an element of a controller which is weak with heat by composing a substrate of a power section of a material having better thermal conductivity than that of a control section.

CONSTITUTION: A power section having a large heat generation and a controller are separately composed to be thermally separated. That is, an upper substrate 1 is composed of an Al_2O_3 substrate, the controller is placed thereon, and a lower substrate 2 having a power element is composed of a sintered AlN having better thermal conductivity than the substrate 1. The substrates 1, 2 are connected by a flexible cable 4, and the substrate 1 is slid to a back side groove 6 in a resin case 5 to be integrated within the case 5.

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